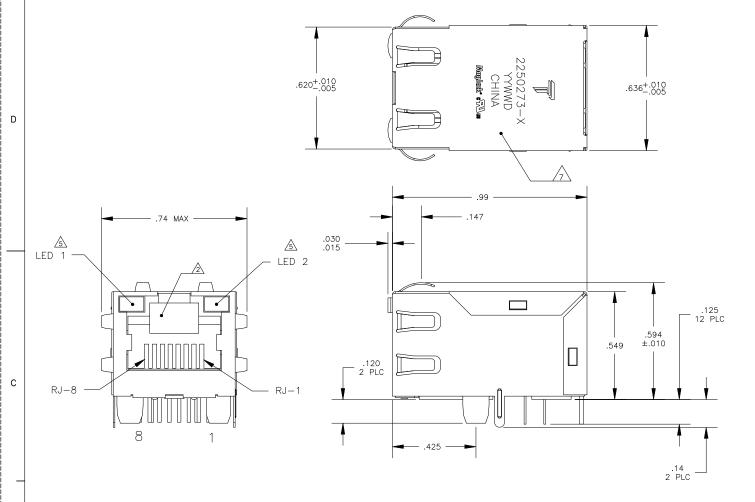
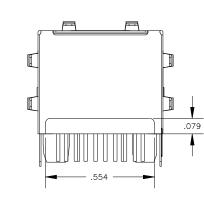
8	7	6	5	4	3	
THIS DRAWING AND THE SUBJECT MATTER SHOWN THEREON ARE CONFIDENTIAL AND THE PROPERTY OF BEL/STEWART/TRP CONNECTOR AND SHALL NOT BE REPRODUCED, COPIED, OR USED IN ANY MANNER WITHOUT THE WRITTEN CONSENT OF TRP CONNECTOR.			PRODUCT MAY BE PROTECTED BY ONE OR MORE OF THE FOLLOWING US PATENTS: 5736910 5939955 6425781 6428361 6554638 6840817 7123117 7429195 7717749 7808751 6217391 6149050 7924130			





MATERIALS: HOUSING - T SHIELD - .00 NICKEL; SOL MOD JACK C NICKEL UNDE SOLDERTAIL LIGHT EMITT WIREFRAME UNDERPLAT MIN MATTE

2 RJ45 JACK PART F.

AGRETICS - APPLICATI - IMPEDANCE - TURNS RA - OPEN CIRCU 8mADC BI. - PERFORMA INSERTIC RETURN

CROSST

COMMON -ISOLATION

4. OPERATING

LEDS ARE D

ASYMMETRI

AGENCY AP

8. THE PART IS PREHEAT TE PEAK SOLDE



THIS DRAWING IS A						
DIMENSIONS:						
INCHES						
÷						
⊕ €						
PRODUCT SPEC						
108-2100						
100-2100						

RCT TDN RDN 6 RDP 8 (7)(1)(3)(5) Есмс2 T1 ] C1Смс1 Ĩ فللغلل SHIELD T2 T3 R2 R1 -////- $\sim$ 

784P10G MAGNETIC SCHEMATIC A

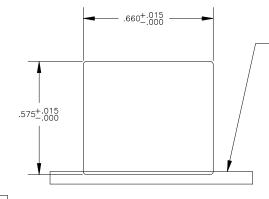
в

А

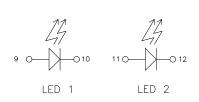
TRP Connecto

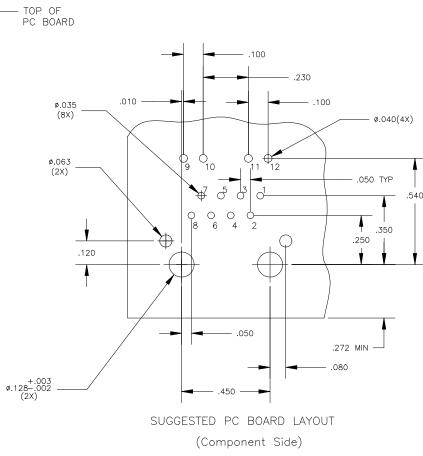
RJ-1 TXP R4 RJ-2 TXN R4 RJ-5 R4 RJ-6 RXN

C1=1000pF. 2kV DECOUPLING CAPACITOR R1-R4 = 75 OHMS, 1/16 W RESISTORS



SUGGESTED PANEL CUTOUT





\_\_\_\_\_

2		1	
P LTR	REVISIONS	DATE DWN APVD	
1 INITIAL RELEAS	SE	08JAN2015 QL TY	
5: THERMOPLASTIC PET POLYESTER FLAMM 08" THICK, C26800 BRASS PREPLATED WI LDER TABS POST-DIPPED WITH SAC SOLD CONTACTS0157" x .018" PHOSPHOR BR JERPLATE, WITH SELECT 50µINCH MIN HAF ILS WITH 100µINCH MIN MATTE TIN AND/O TING DIODE(LED) - DIFFUSED EPOXY LENS E LEADS PREPLATED WITH 80µINCH SILVE TE OVER 40µINCH COPPER UNDERPLATE; F TIN AND/OR SAC SOLDER DIP OR PURE TI CAVITY CONFORMS TO FCC RULES AND RE 5 ION: 10/100 BASE-T E: 100 OHMS TIO (CHIP:CABLE): TX = 1:1, RX = 1:1	TH 30µINCH MIN SEN DER. ONZE, 50µINCH MIN R GOLD FINISH PLA R SAC SOLDER DIP , .020" × .020" CARB R OVER 40µINCH NIC POST-PLATED WITH N SOLDER DIP.	1I-BRIGHT OVERALL TE. SON STEEL CKEL 100μINCH	D
UIT INDUCTANCE (OCL): 350 µH MIN @100kH IAS FROM 0°C TO 70°C, TX AND RX ANCE @ 25°C: ION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 30 18-20LOG(f/30)dB MIN FROM 30. 12dB MIN FROM 60.1MHz TO 80MH TALK ATTENUATION: 35dB MIN FROM 40 N MODE REJECTION RATIO (CMRR): 30dB M N VOLTAGE: COMPLIES WITH IEEE802.3 20 TEMPERATURE: FROM 0°C TO +70°C. DRIVEN WITH CONSTANT CURRENT AT APP E DOMINANT WAVELENGTH ( <b>A</b> D): GREEN 56 FORWARD VOLTAGE (VF): GREEN 2.2V T DOMINANT WAVELENGTH ( <b>A</b> D): YELLOW S	100MHz MHz 1MHz TO 60MHz 1z Hz TO 40MHz .1MHz TO 100MHz IN FROM 0.5MHz TO 02, PARA 23.5.1.1, IT PROX 20mA. v8 nm TYP @ IF=20m YP @ IF=20mA 588 nm TYP @ IF=20	ЕМ Ь. А	С
FORWARD VOLTAGE (VF): YELLOW 2.1V CONNECTIONS ARE FOR NIC CONFIGURATIO RIC, AND DO NOT SUPPORT AUTO-MDI/MDI CTOR LOGO, PART NUMBER, DATE CODE, C PPROVAL MARKING IN APPROXIMATE LOCA IS RECOMMENDED FOR WAVE SOLDERING F IEMPRATURE IS 120°C TO 160°C, 120 SECON DERING TEMPERATURE IS 260 °C MAX, 10 S	N. THE MAGNETICS X. COUNTRY OF ORIGIN ATION SHOWN. PROCESS, NDS TO 180 SECONDS	AND	В
2250273-2 (NO EM 2250273-2 (NO EM 2250273-2 (NO EM 2250273-2 (NO EM 25000000000000000000000000000000000000	GREEN 2	TAB UP W/ LED	A

## **Mouser Electronics**

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Bel: 2250273-1